Die based semiconductor solutions for custom packaging of sensors, mems and high reliability microelectronics

MICROSS COMPONENTS LTD SPECIALISES IN DESIGN, ASSEMBLY AND ELECTRICAL TEST OF SEMICONDUCTOR BARE DIE SOLUTIONS FOR A DIVERSE RANGE OF INDUSTRIAL, MEDICAL, AUTOMOTIVE & AEROSPACE APPLICATIONS.
Die based semiconductor solutions for custom packaging of sensors, mems and high reliability microelectronics

SERVICES
- Die & Wafer Processing
- Bare Die Distribution
- Chip On Board
- Hi-Rel Hermetic Packaging
- Die Attach & Wirebond
- Fine Pitch & Staggered Bonding
- Mixed SMT & Die Assembly
- Electrical Burn In & Test
- ASIC Design, Circuit Design
- Miniaturisation using Bare Chip
- Multi-Chip Modules
- Full Custom Packaging Solutions

TECHNOLOGY APPLICATIONS
- Medical Fluidics
- Gas Sensing
- Anaesthetic Delivery
- Automotive Sensors
- Hi-Rel Military Grade
- Space Grade
- Down Hole High Temperature
- MEMS
- RF & Microwave
- LED Arrays
- Photovoltaic Modules

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